CDM I Series Modular Data Center:

Designed for AI inference at the edge, offering low-latency and right-sized capacity.

The **CDM I Series** is a purpose-built modular data center designed and built in the USA for scalable AI inference and latency-sensitive applications. Supporting 50–250+ kW per rack and up to 500 kW per module with air cooling—or 1+ MW with liquid and air—it delivers compact, all-in-one architecture for fast, flexible deployment and future-ready scalability at the edge.

Key Features:

- **Edge-Optimized:** Compact, all-in-one design for edge environments.
- **Flexible Cooling:** DX air-cooled, chilled water, and liquid cooling configurations.
- **Scalable Capacity:** Up to 500 kW (air) or 1 MW (air + liquid).
- **Lower TCO:** Integrated design reduces upfront and operating costs.
- **Open OEM Integration:** Compatible with leading chip and IT hardware manufacturers.
- **Certified & Rugged:** UL2755, NEMA Rated, seismic, wind, and snow ratings.

Designed for the Edge.

Optimized for distributed AI inference at the Edge, the I Series integrates power and cooling in a single footprint for simplified installation and lower TCO. Flexible cooling options—including DX air, chilled water, and hybrid air-liquid—ensure adaptability across diverse environments. The I Series provides reliable infrastructure for telecom, healthcare, education, government, and other edge deployments.

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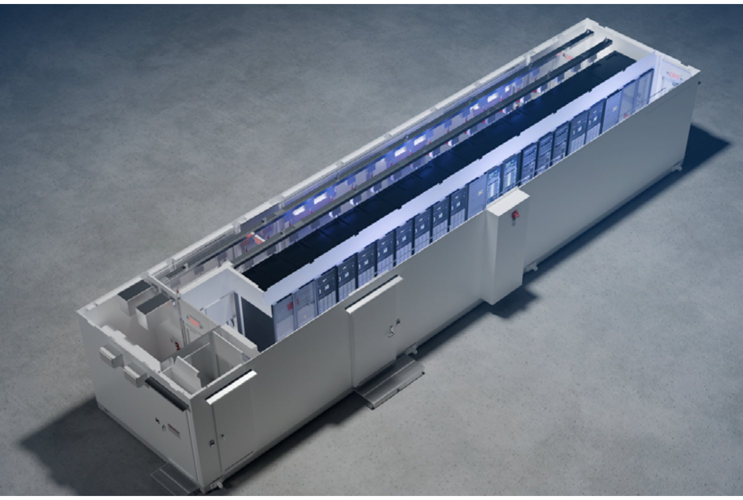
Features	CDM I Series Specifications
Dimensions (approx.):	IT Module: 49' L, 12' W, 12' H Overhead Cooling Module: 49' L, 12' W, 4' H All-in-one compact design with overhead cooling module
Density:	Engineered for 50–250+ kW per rack

Capacity:	• Air or Air/Liquid Cooling
	• Top Hat Cooling System (mix and match to application)
	  • 50kW or 100kW units for N and N+1
	  • Chilled water, DX, Liquid/DX
	• Supports multiple CDU/cold plate cooling solutions
	• Supports air cooling at 600kW max

Power:	Flexible busway or Optional power cable support 480V/415V standard, 208V optional
Weight:	IT Module 60,000 lbs., Top Hat AHU: 15,000 lbs., 8-point bottom lift.
Deployment Speed:	30–50% faster than traditional stick-built data centers.
Compliance:	UL2755 compliance, NEMA rated, meets Seismic C; sustains wind speeds up to 120 mph; snow loads up to 30 PSF; can be configured for higher environmental requirements.
OEM Compatibility:	Supports multiple chip, IT hardware and infrastructure OEM equipment with no vendor lock-in, allowing customers to determine best technology for their application.
Reliability:	Supports Tier 1–4 architectures for uptime and redundancy
Lifecycle Services:	Conceptualization and design, Industrial fabrication, Factory Acceptance Testing (FAT), Deployment and commissioning, Long-term maintenance and SLAs.
Technology Neutral:	Supports multiple IT hardware and infrastructure OEM equipment with no vendor lock-in, allowing customers to determine best technology for their application



Built for Scale. Engineered for Performance.

Adaptable for evolving AI workloads and edge environments, the I Series delivers resilient, right-sized capacity with flexible cooling and power options. Its compact, all-in-one design ensures efficiency, scalability, and reliability for the future of distributed AI inference.

Let's drive modular innovation and efficiency – together.

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For full solutions details, visit https://cd-modular.com